

Minimum inner layer thickness

Minimum inner layer thickness – this parameter shows the thinnest inner layer used by Brandner Electronics in the manufacture of multilayer printed circuit boards.

Please note that the presented thickness (0.1 mm) shows the thickness of the isolating layer used for manufacturing multilayer boards, which is added the thickness of the copper foil – i.e. in the case of using 18 μ foil, the total thickness of the material is 0.136 mm:

Innerlayer foil	18 μ m	0.018
Innerlayer	High Tg 0,1mm 18 μ m/18 μ m	0.100
Innerlayer foil	18 μ m	0.018
Material thickness (mm) $\pm$ 10%		0.136